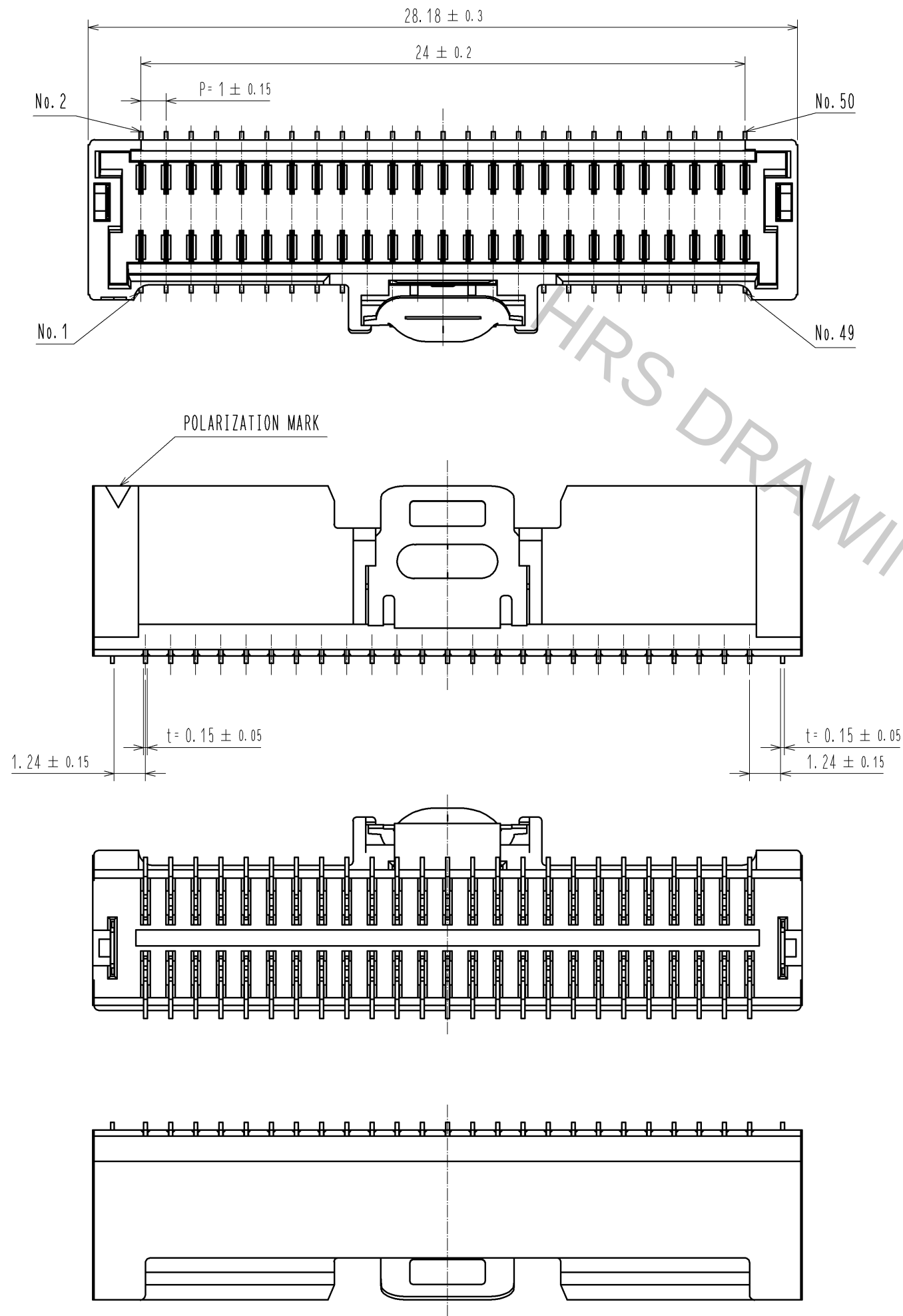
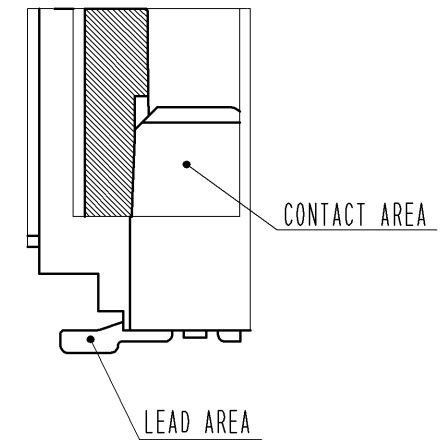


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In case that the application demands a high level of reliability, such as automotive,
please contact a company representative for further information.



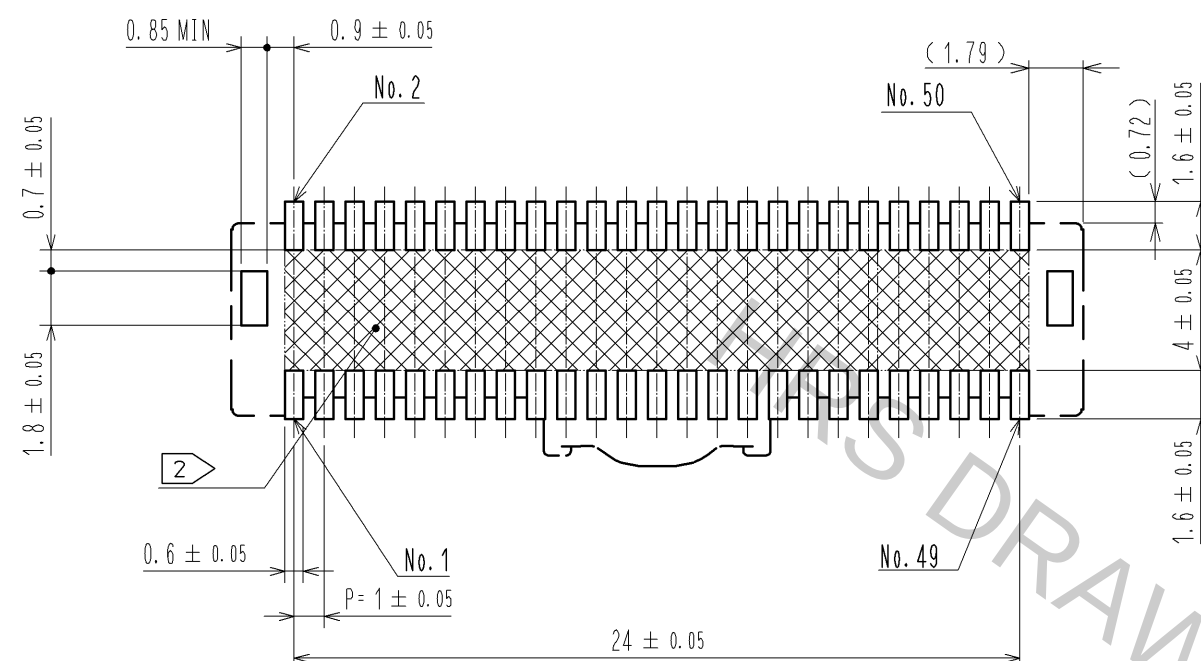
A (10:1)



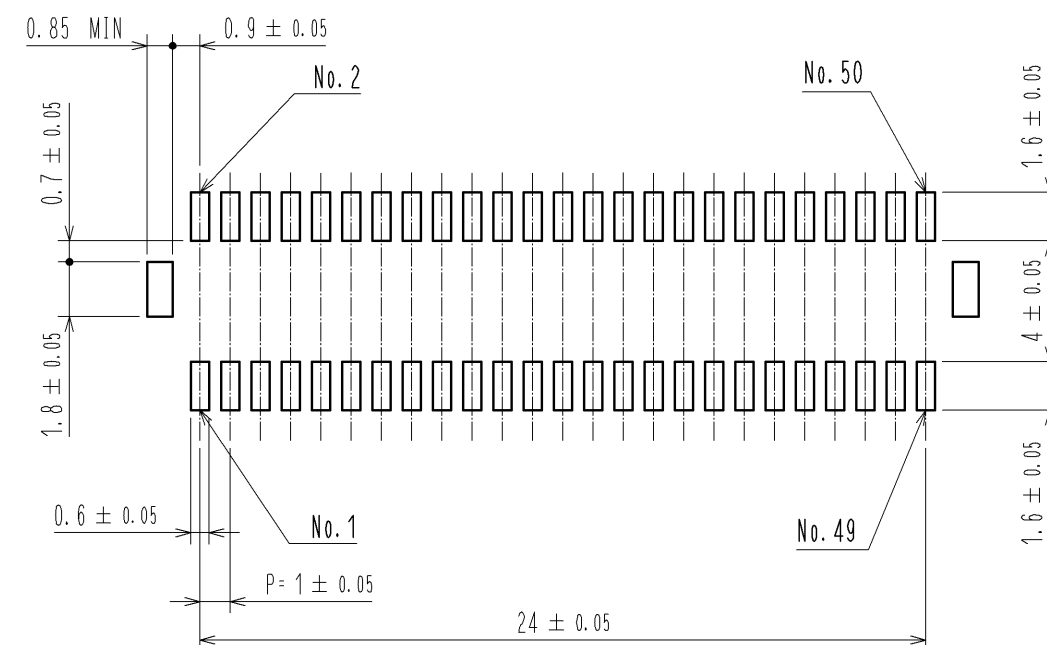
- NOTES
1. LEAD CO-PLANARITY SHALL BE 0.1 mm MAX.
 2. AREA INDICATED MUST BE FREE OF CONDUCTIVE TRACES OR THE CONDUCTIVE TRACES MUST BE COVERED BY RESIST FILM.
 3. PLEASE CONSULT HIROSE WHEN THE PRODUCT IS MOUNTED TO EPC.

3	BRASS	CONTACT AREA : Au PLATING 0.05μm MIN.	8	PS	REEL, BLACK
		LEAD AREA : Au PLATING 0.05μm MIN.	7	POLYESTER	CLEAR
		UNDERPLATING : Ni PLATING 1μm MIN.	6	PS	CLEAR
2	BRASS	CONTACT AREA : Au PLATING 0.05μm MIN.	5	STAINLESS STEEL	-
		LEAD AREA : Au PLATING 0.05μm MIN.	4	BRASS	SURFACE : Sn PLATING 1μm MIN.
		UNDERPLATING : Ni PLATING 1μm MIN.			UNDERPLATING : Ni PLATING 0.5μm MIN.
1	LCP	NATURAL, UL94V-0			
NO.	MATERIAL	FINISH, REMARKS	NO.	MATERIAL	FINISH, REMARKS
UNITS mm		SCALE FREE	COUNT		DESCRIPTION OF REVISIONS
					DESIGNED
					CHECKED
					DATE
HIROSE ELECTRIC CO., LTD.		APPROVED : KI. AKIYAMA	14.10.17	DRAWING NO.	EDC3-330237-05
		CHECKED : TS. FUKUSHIMA	14.10.17	PART NO.	DF50-50DP-1V(61)
		DESIGNED : HT. SATO	14.10.17	CODE NO.	CL665-0011-1-61
		DRAWN : MI. SAKIMURA	14.10.16		

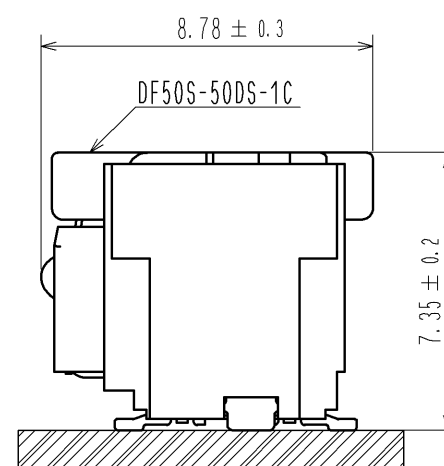
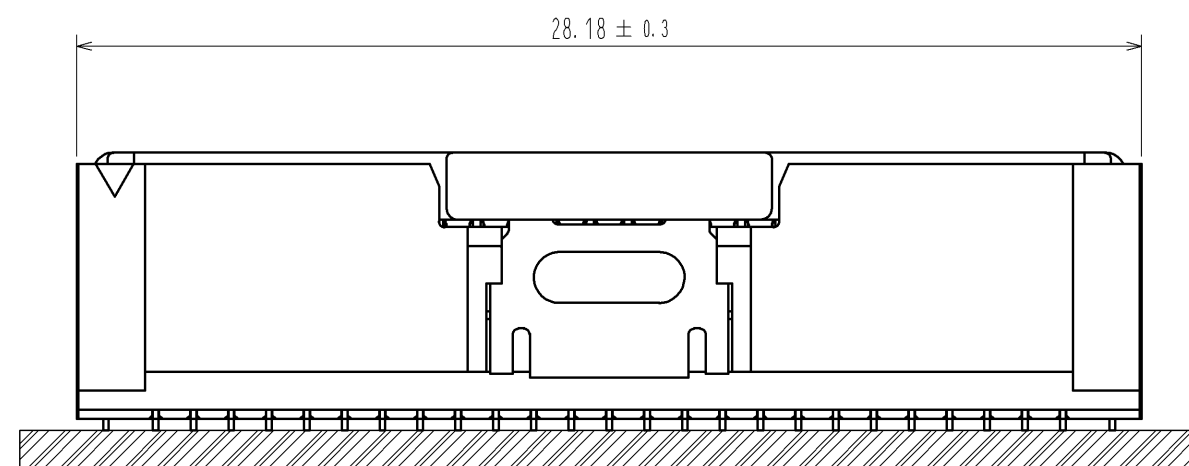
RECOMMENDED PCB LAYOUT
(MOUNTING SURFACE SIDE) (FREE)



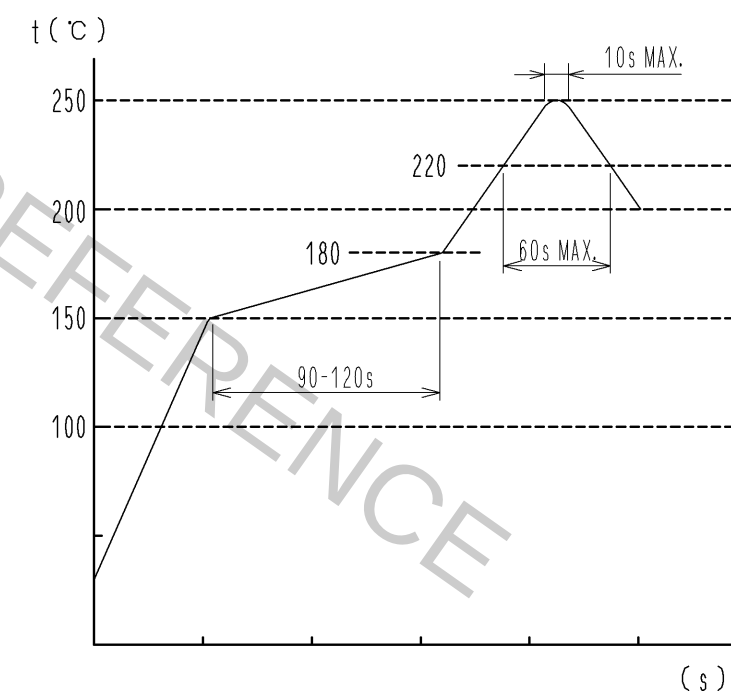
RECOMMENDED METAL MASK (FREE)
THICKNESS : 0.1mm



MATING FIGURE (5 : 1)



REFLOW TEMPERATURE PROFILE
USING LEAD-FREE SOLDER PASTE(REFERENCE)



NUMBER OF REFLOW CYCLES : 2 CYCLES MAX.
THE TEMPERATURE OF THIS PROFILE IS MASURED ON THE LEAD TERMINAL.

WE RECOMMEND PERFORMING AN EVALUATION UNDER THE MOUNTING
CONDITIONS YOU WILL BE USING BECAUSE IT COULD BE AFFECTED
BY ANY CONDITION:TYPE OF SOLDER PASTE, SIZE OF PCB, MOUNTING
METAL etc.

HRS

DRAWING NO.	EDC3-330237-05
PART NO.	DF50-50DP-1V(61)
CODE NO.	CL665-0011-1-61

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